

Customer No.: 31561  
Docket No.: 10041-US-PA  
Application No.: 10/605,660

### AMENDMENTS

#### In The Claims

Claims 1-10. Cancelled.

Claim 11. (Currently amended ) A high density semiconductor package, comprising:

a substrate, having a surface;

a first package module, being disposed on the surface of the substrate; and

a plurality of second package modules, being disposed on the surface of the substrate surrounding the first package module, wherein each of the second package modules has a corner near a corresponding one side of the first package module, wherein the corner is included from two sides of a corresponding one of the second package modules and the two sides are not parallel to the corresponding one side of the first package module. ~~a corner of each of the second package modules face a side of the first package module~~

Claim 12. (currently amended) The high density semiconductor package as claimed in claim 11, wherein a ~~gap width~~ between the corner of the corresponding one of the second package modules and the corresponding one side of the first package module is larger than 2 mm.

Claim 13. (original) The high density semiconductor package structure as claimed in claim 11, wherein the first package module is arranged coplanar with the second package modules.

Claim 14. (original) The high density semiconductor package as claimed in claim 11,

Customer No.: 31561  
Docket No.:10041-US-PA  
Application No.: 10/605,660

wherein the first package module comprises:

a chip;

a plurality of bumps located between the chip and the substrate; and

an underfill located between the chip and the substrate and enveloping the bumps.

Claim 15. (original) The high density semiconductor package as claimed in claim 11,

wherein each of the second package modules comprises:

a chip;

a plurality of bumps located between the chip and the substrate; and

an underfill located between the chip and the substrate and enveloping the bumps.

Claims 16-23. Cancelled.

Claim 24. (cancelled)

Claim 25. (currently amended) The high density semiconductor package as claimed in claim 11, wherein ~~the first package module is arranged substantially non-orthogonal to the second package module~~ the first package module has four sides, and the number of the second package modules is four, respectively facing to the four sides.

Claim 26. (new) The high density semiconductor package as claimed in claim 11, wherein the corner of each of the second package modules face the side of the first package module by a

Customer No.: 31561  
Docket No.:10041-US-PA  
Application No.: 10/605,660

direction substantially perpendicular to one of the sides of the first package module.

Claim 27. (new) A high density semiconductor package, comprising:

a substrate, having a surface;

a first package module, being disposed on the surface of the substrate; and

a plurality of second package modules, being disposed on the surface of the substrate  
surrounding the first package module,

wherein the first package module has first sides and each of the second package modules  
has second sides, wherein the first sides are not parallel to the second sides.